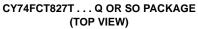
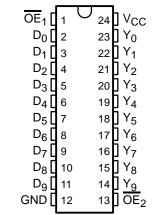
- Function, Pinout, and Drive Compatible
 With FCT, F, and AM29827 Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- 3-State Outputs
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT827T
 - 32-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT827T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current

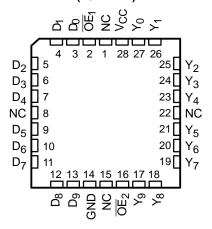
description

The 'FCT827T devices are 10-bit bus drivers that provide high-performance bus-interface buffering for wide data/address paths or buses carrying parity. The 10-bit buffers have NANDed output enables for maximum control flexibility. The 'FCT827T devices are designed high-capacitance-load drive capability, while providing low-capacitance bus loading at both inputs and outputs. All outputs are designed for low-capacitance bus loading high-impedance state.





CY74FCT827T . . . L PACKAGE (TOP VIEW)



NC - No internal connection

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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ORDERING INFORMATION

TA	PAC	(AGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
-40°C to 85°C	QSOP – Q	Tape and reel	4.4	CY74FCT827CTQCT	FCT827C	
	SOIC - SO	Tube	4.4 CY74FCT827C		FCT827C	
	3010 - 30	Tape and reel	4.4	CY74FCT827CTSOCT	FC1627C	
-40 C to 65 C	QSOP – Q	Tape and reel	8	CY74FCT827ATQCT	FCT827A	
	SOIC – SO Tube		8	CY74FCT827ATSOC	FCT827A	
	3010 - 30	Tape and reel	8	CY74FCT827ATSOCT	FC1627A	
−55°C to 125°C	LCC – L Tube		9	CY54FCT827ATLMB		

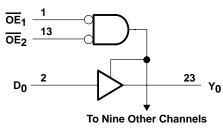
[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

	INPUTS		OUTPUT	FUNCTION
OE ₁	OE ₂	D	Υ	FUNCTION
L	L	L	L	Transparent
L	L	Н	Н	Transparent
Н	Х	Χ	Z	2 atata
Х	Н	Χ	Z	3-state

H = High logic level, L = Low logic level, X = Don't care, Z = High-impedance state

logic diagram (positive logic)



Pin numbers shown are for the Q and SO packages.

absolute maximum rating over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range to ground potential	\dots –0.5 V to 7 V
DC input voltage range	\dots –0.5 V to 7 V
DC output voltage range	\dots –0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	61°C/W
SO package	46°C/W
Ambient temperature range with power applied, T _A	. -65°C to 135°C
Storage temperature range, T _{stq}	. -65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 2)

		CY54FCT827T			CY7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
ІОН	High-level output current			-12			-32	mA
l _{OL}	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEGT CONDITION	10	CY	CY54FCT827T			CY74FCT827T			
PARAMETER		TEST CONDITION	NS	MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	X UNIT	
V	$V_{CC} = 4.5 \text{ V},$	$I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V	
VIK	V _{CC} = 4.75 V,	$I_{IN} = -18 \text{ mA}$						-0.7	-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -12 \text{ mA}$		2.4	3.3						
Voн	V _{CC} = 4.75 V	$I_{OH} = -32 \text{ mA}$					2			V	
	VCC = 4.75 V	$I_{OH} = -15 \text{ mA}$					2.4	3.3			
Voi	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 32 \text{ mA}$			0.3	0.55				V	
VOL	$V_{CC} = 4.75 \text{ V},$	$I_{OL} = 64 \text{ mA}$						0.3	0.55	٧	
V_{hys}	All inputs				0.2			0.2		V	
	$V_{CC} = 5.5 \text{ V},$	$V_{IN} = V_{CC}$				5				μΑ	
lj .	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = V_{CC}$							5	μΑ	
lu.	$V_{CC} = 5.5 \text{ V},$	V _{IN} = 2.7 V				±1				μΑ	
lН	$V_{CC} = 5.25 \text{ V},$	$V_{1N} = 2.7 \text{ V}$							±1	μΑ	
۱۱۲	$V_{CC} = 5.5 V$,	$V_{IN} = 0.5 V$				±1				μΑ	
'IL	$V_{CC} = 5.25 \text{ V},$	$V_{IN} = 0.5 V$							±1	μΛ	
lozh	$V_{CC} = 5.5 V$,	V _{OUT} = 2.7 V				10				μΑ	
'OZH	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 2.7 V							10	μΑ	
lozi	$V_{CC} = 5.5 V$,	V _{OUT} = 0.5 V				-10				μΑ	
lozL	$V_{CC} = 5.25 \text{ V},$	V _{OUT} = 0.5 V							-10	μΑ	
los‡	$V_{CC} = 5.5 \text{ V},$	$V_{OUT} = 0 V$		-60	-120	-225				mA	
iOS+	$V_{CC} = 5.25 \text{ V},$	$V_{OUT} = 0 V$					-60	-120	-225	ША	
l _{off}	$V_{CC} = 0 V$,	V _{OUT} = 4.5 V				±1			±1	μΑ	
loo	$V_{CC} = 5.5 \text{ V},$	$V_{IN} \le 0.2 V$	$V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.1	0.2				mA	
lcc			$V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.1	0.2	шА	
Alco	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3$				0.5	2				mA	
∇ICC	$V_{CC} = 5.25 \text{ V}, V_{IN} =$	3.4 V\$, f ₁ = 0, Ou	itputs open					0.5	2	IIIA	

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ios tests should be performed last.

 $[\]$ Per TTL-driven input ($V_{IN} = 3.4 \text{ V}$); all other inputs at V_{CC} or GND

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETER	_	TEGT CONDITIONS		CY	54FCT82	27T	CY	74FCT82	:7T		
PARAMETER		TEST CONDITIONS		MIN TYP [†] MAX I				TYP [†]	MAX	UNIT	
. п	$V_{CC} = 5.5 \text{ V}$, One input switching at 50% duty cycle, Outputs open, \overline{OE}_1 or $\overline{OE}_2 = \text{GND}$, $V_{IN} \le 0.2 \text{ V}$ or $V_{IN} \ge V_{CC} - 0.2 \text{ V}$				0.06	0.12				mA/	
ICCD	V_{CC} = 5.25 V, One in Outputs open, \overline{OE}_1 over $V_{IN} \le 0.2$ V or $V_{IN} \ge 0.2$	or $\overline{OE}_2 = GND$,	% duty cycle,					0.06	0.12	MHz	
		One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4					
	$V_{CC} = 5.5 \text{ V},$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4					
	Outputs open, OE ₁ or OE ₂ = GND		$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1.6	3.2			TYP [†] MAX		
IC#		at 50% duty cycle	V _{IN} = 3.4 V or GND		4.1	13.2				mA	
I IC		One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	0.7 1.4	IIIA	
	V _{CC} = 5.25 V,	at 50% duty cycle	V _{IN} = 3.4 V or GND					1	2.4		
	Outputs open, OE ₁ or OE ₂ = GND	10 bits switching at f ₁ = 2.5 MHz	ing $V_{IN} \le 0.2 \text{ V or}$					1.6	3.2		
		at 50% duty cycle	V _{IN} = 3.4 V or GND					4.1	13.2		
C _i			_		5	10		5	10	pF	
Co					9	12		9	12	pF	

This parameter is derived for use in total power-supply calculations.

 $^{\#}$ IC = ICC + \triangle ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

Where:

I_C = Total supply current

ICC = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

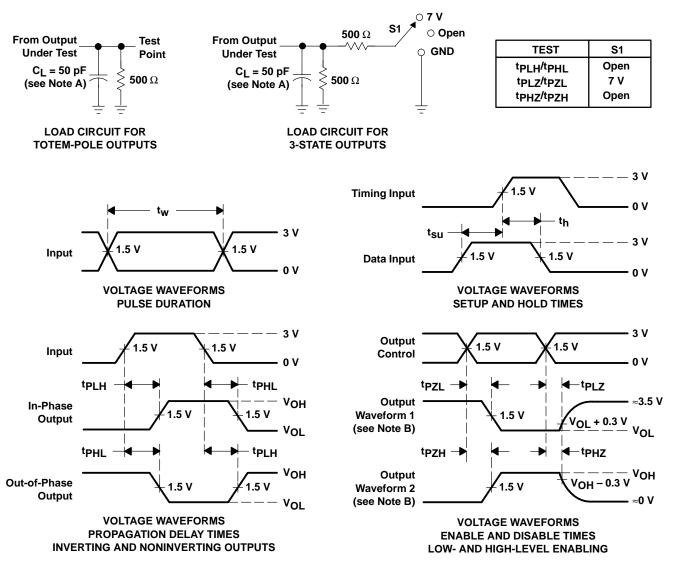
 \parallel Values for these conditions are examples of the ICC formula.



switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	TEST LOAD	CY54FCT	827AT	CY74FCT	827AT	CY74FCT	827CT	UNIT
I ANAMILIEN (INP	(INPUT)	(OUTPUT)	IEST LOAD	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _{PLH}	D	Y	$C_L = 50 \text{ pF},$	1.5	9	1.5	8	1.5	4.4	no
tPHL	ט	ī	$R_L = 500 \Omega$	1.5	9	1.5	8	1.5	4.4	ns
tPLH	D	Y	C _L = 300 pF,	1.5	17	1.5	15	1.5	10	ns
tPHL	ט	ī	$R_L = 500 \Omega$	1.5	17	1.5	15	1.5	10	115
t _{PZH}	ŌĒ	Y	C _L = 50 pF,	1.5	13	1.5	12	1.5	7	ns
tPZL	OE	ī	$R_L = 500 \Omega$	1.5	13	1.5	12	1.5	7	115
^t PZH	ŌE	Y	C _L = 300 pF,	1.5	25	1.5	23	1.5	14	ns
t _{PZL}	OL	T	$R_L = 500 \Omega$	1.5	25	1.5	23	1.5	14	115
t _{PHZ}	ŌĒ	Y	C _L = 5 pF,	1.5	9	1.5	9	1.5	5.7	20
t _{PHL}		ť	$R_L = 500 \Omega$	1.5	9	1.5	9	1.5	5.7	ns
t _{PHZ}	ŌĒ	Y	$C_L = 50 \text{ pF},$	1.5	10	1.5	10	1.5	6	no
t _{PHL})E	ſ	$R_L = 500 \Omega$	1.5	10	1.5	10	1.5	6	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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